

FBHA S Series

Chip Ferrite Bead High Current Type
Size 0603

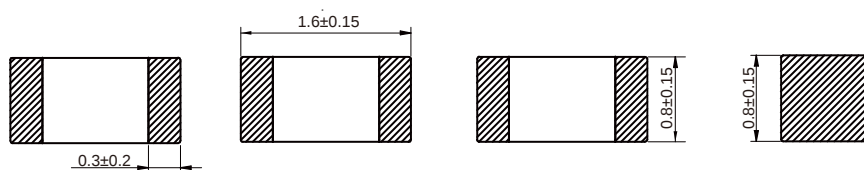
FEATURES

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- Compared to the FBA series, has low direct current resistance for
- with 2 materials of different features for countermeasures against everything from general signals to high-speed signals.
- Performs well even in signal lines where low direct current resistance is required.
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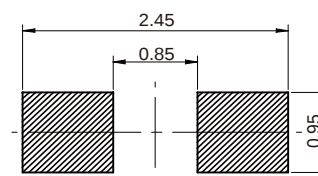
APPLICATION

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Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

	(Ω)		(Ω)	(mA)
FBHA0603S-300-502R	30	±25%	0.010	5000
FBHA0603S-600-402R	60	±25%	0.020	4000
FBHA0603S-800-302R	80	±25%	0.030	3000
FBHA0603S-101-302R	100	±25%	0.030	3000
FBHA0603S-121-302R	120	±25%	0.035	3000
FBHA0603S-151-252R	150	±25%	0.040	2500
FBHA0603S-221-232R	220	±25%	0.050	2300
FBHA0603S-301-222R	300	±25%	0.070	2200
FBHA0603S-471-202R	470	±25%	0.090	2000
FBHA0603S-601-202R	600	±25%	0.095	2000
FBHA0603S-102-152R	1000	±25%	0.150	1500

Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$

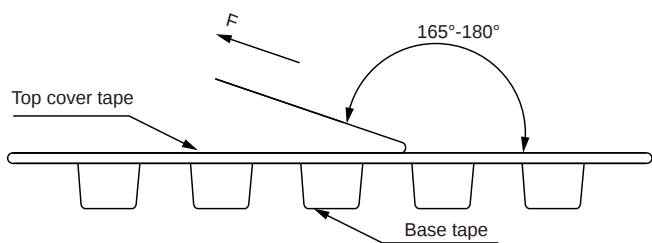
Soldering Reflow:

Packaging Information:

Tape Dimension:

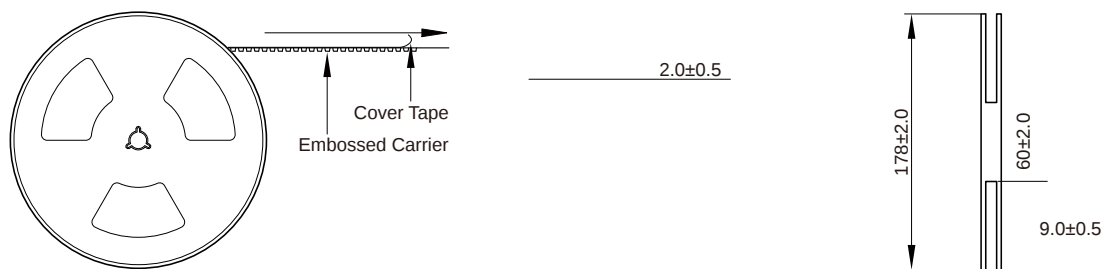
Series

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.14 to 0.58 N

Reel Dimension: [mm]



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C , humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C .
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